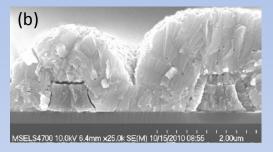
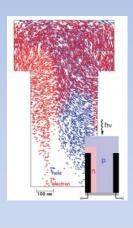
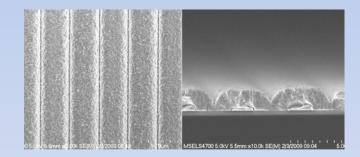
Metallurgy Division

Back Contact Thin Film Photovoltaics & My PV System: 9 kW and a Rooftop







Daniel Josell Metallurgy Division Material Measurement Laboratory For IEEE Photonics Society, DC Chapter Meeting October 17, 2012





Talk Outline

Metallurgy Division

Outline:

Introduction to solar panels and devices

Back contact silicon devices

Back contact thin film devices

My PV system



1st Generation Technologies

Metallurgy Division



Pyramidal surface with silicon nitride antireflection layer Burried contact Back contact · Antireflection lay

Light hits the photovoltaic device

Each photon that enters with energy greater than the bandgap creates an electron-hole pair Carriers are separated by a junction between p- and n-type material and move to +/- electrodes Those that don't recombine on the way or at the interfaces supply current Geometries are optimized to maximize absorption of light and minimize carrier recombination



2nd Generation Technologies Metallurgy Division

Thin film devices

- The bandgap is maximum energy extractable from a photon
- Direct bandgap absorbers such as a-Si, CdTe, CIS or CIGS
- Otherwise similar 1D geometry:
 - Planar contact/p-type/n-type/contact



CIGS (Honda Bldg)



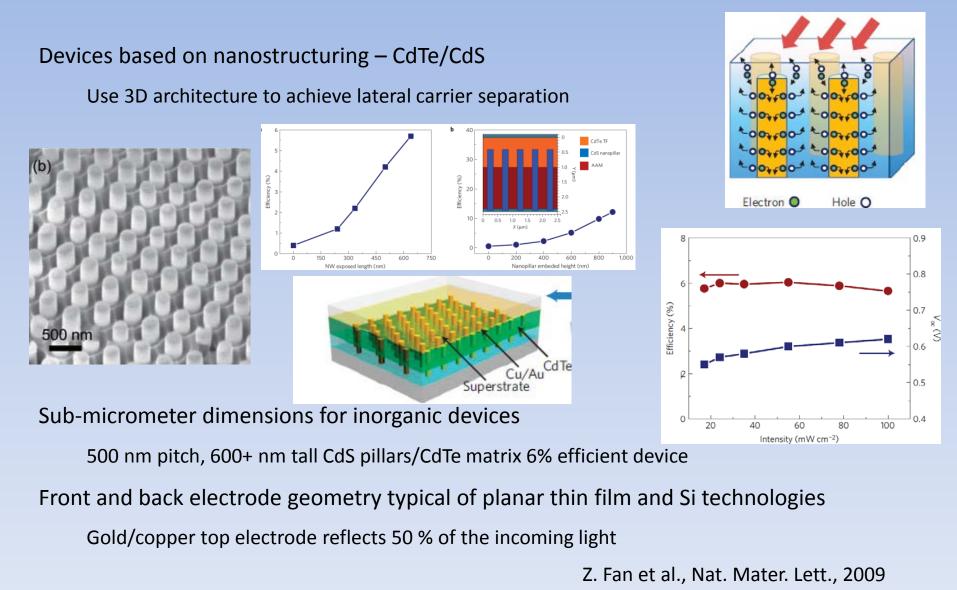


Thin film technologies based on thin film CdTe can now be produced for less than \$1/watt, well below crystalline Si costs. The present cost leader produced at \$0.73/watt ; production panel efficiency exceeding 12 % and record panel 14.7%



3rd Generation Technologies

Metallurgy Division



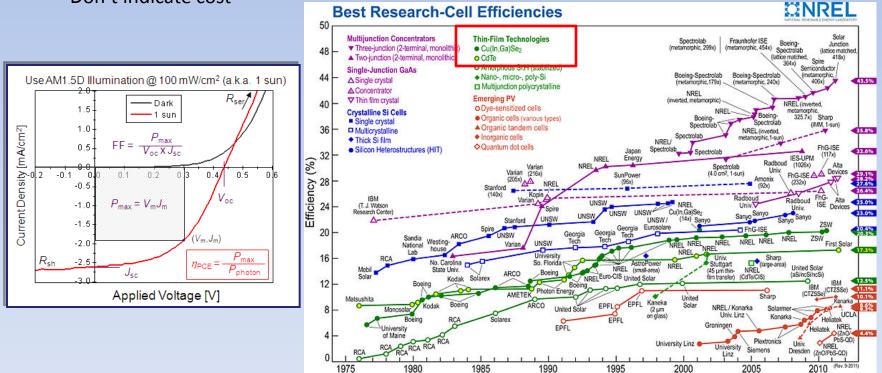
NIST

"Hero" Photovoltaic Devices

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Numbers in the lab differ from commercial module efficiencies

- Do indicate the potential efficiencies of panel-scale technologies
- Don't indicate difficulty of achieving performance
- Don't indicate cost

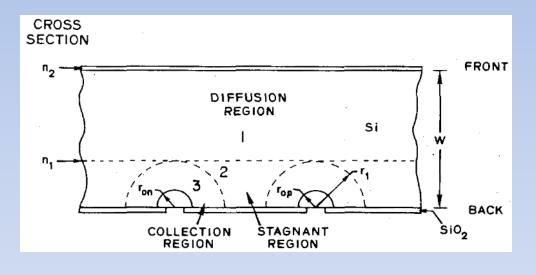


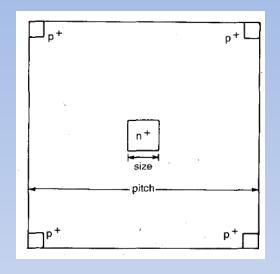


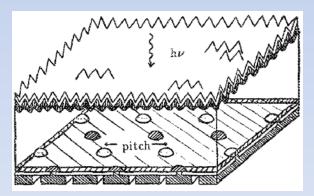
Silicon Back Contact Technologies Metallurgy Division

Some silicon photovoltaics use a dual back contact geometry

Record setting efficiencies in 1989 over 22% at 1 sun and 28% under 150 sun







R.A. Sinton and R.M. Swanson, IEEE Trans. Electron. Dev., 1987

R.R. King et al, , Appl. Phs. Lett, 1989

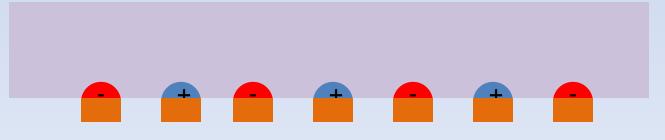


Silicon Back Contact Technologies Metallurgy Division

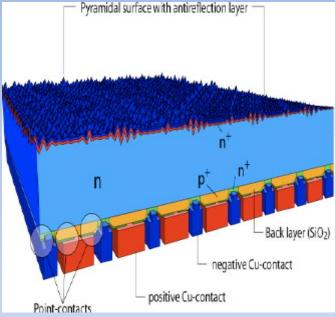
(Dual) back contact geometry No light blocked by front contact metal lines or transparent conducting oxide Place dopants and contacts through successive patterning steps

Successive aligned patterning steps

More difficult for dimensions of thin film and nanostructured devices





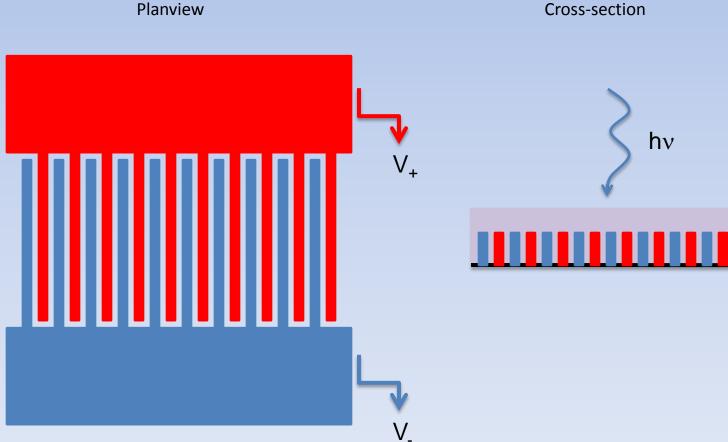


Back Contact Template

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Start with patterned electrodes

• Utilize the interdigitated "comb" structures of microelectronics as electrodes and deposit semiconductor on them to define device dimensions and geometry

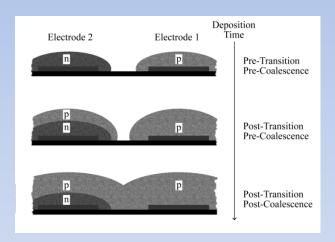


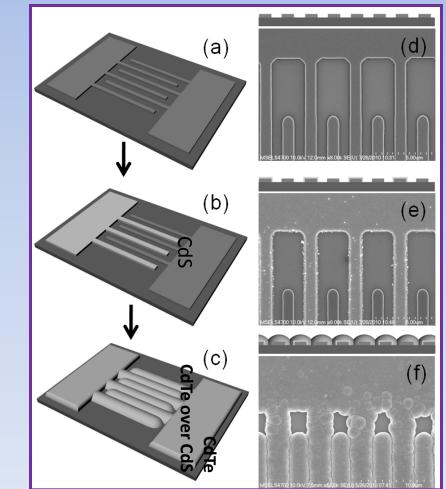
Planview

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Devices based on CdS/CdTe system

Electrodeposit CdS on one electrode Electrodeposit CdTe on both electrodes





Pros:

- Industrially relevant materials system
- Eliminate detrimental UV absorption in "window" layer (i.e., CdS behind the CdTe)
- Eliminate top conducting oxide and metallization that block incoming light
- Create surface topography that could enhance light absorption
- Material and process generic after first electrodeposition step
- Electrodeposition yields extremely high material utilization

Cons:

- Electrode patterning length scale dictated by recombination length (carrier lifetime)
- Electrodes present during all processing



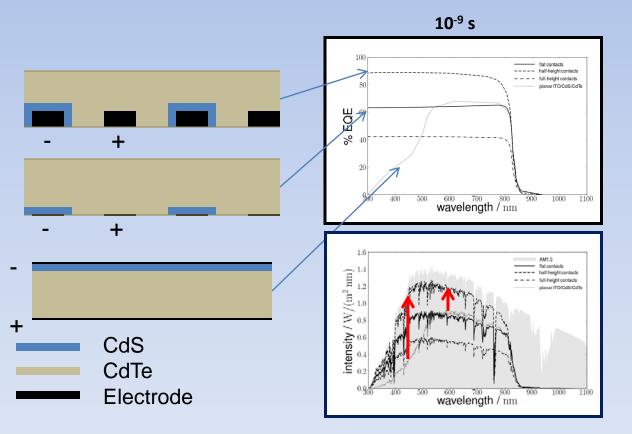
CdS/CdTe Modeling

Metallurgy Division

Modeling dual back-contact geometry : CdS behind CdTe

100 nm CdS under 2 μ m CdTe in the 2 μ m pitch 3D devices : different electrode heights vs planar

These early modeling results ignore recombination at interfaces/surfaces



External Quantum Efficiency:

EQE – fraction of photons that actually generate current (as function of wavelength)

Taller electrodes are beneficial as they reduce carrier diffusion length

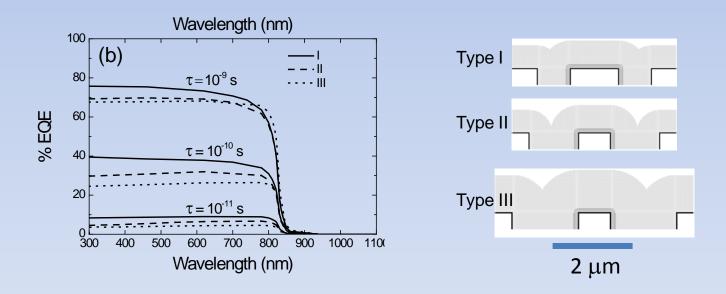
CdS/CdTe Modeling

Metallurgy Division

Modeling device performance

External quantum efficiency and device performance are predicted to be dominated by the carrier lifetime

3D surface topography also influences performance





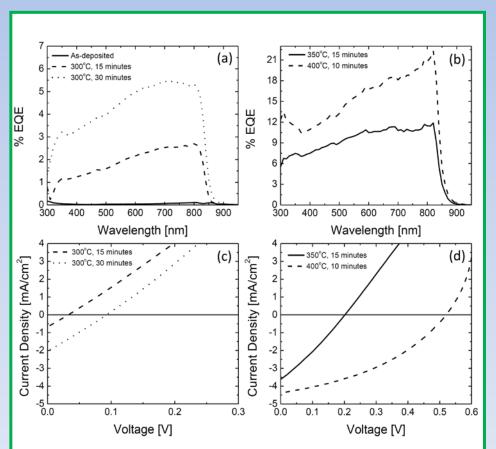
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Device performance improves with annealing

Also required for CdS/CdTe planar devices (often in the presence of CdCl₂)

Device efficiency of 0.9 % consistent with dimensions, microstructure, non-ideal contacts

Resistivity is an issue in these devices





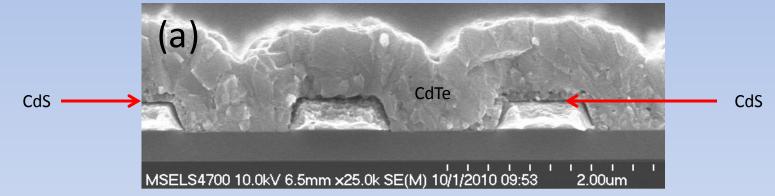
Material Measurement Laboratory

Metallurgy Division

- CdTe grain size increases and CdS/CdTe junction improves with annealing
 - Performance improves

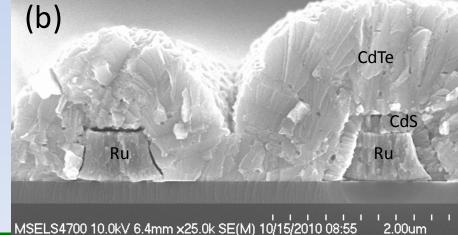
Electrodeposited CdTe reacts with the Pt electrodes during annealing after CdCl₂ solution dip

• Voids form at the interface prior to optimum annealing for the semiconductor and device fails



Electrodeposited CdTe does not react with Ru electrodes during annealing after CdCl₂ solution dip

• Adhesion not ideal



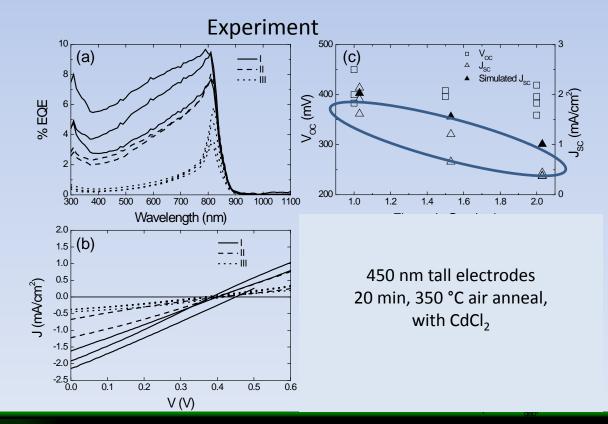


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Performance of devices annealed at 350 °C for 20 min exhibits trends consistent with transport limitation expected for low temperature anneal.

- J_{sc} trends with the width of the gap between electrodes consistent with simulation
- V_{oc} only weakly trends with the gap

Performance limited by annealing conditions and contact to CdS



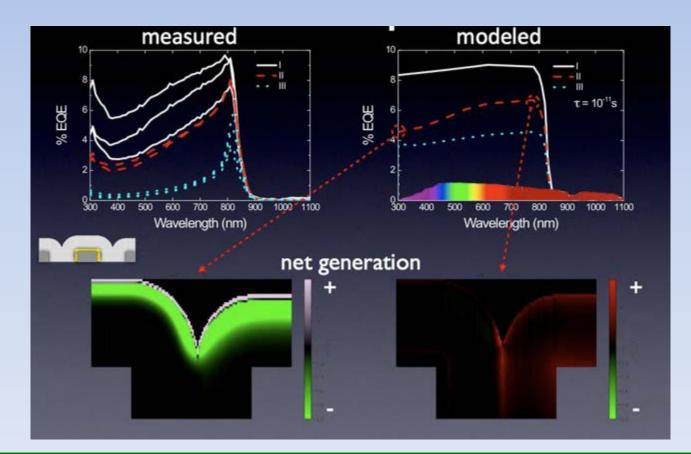


CdS/CdTe Evaluation

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Modeling suggests origin of observed EQE behavior for these materials/devices

- High density of carriers generated near the surface for shorter wavelengths results in increased recombination due to poor quality of material (short lifetime)
- •Low lamp intensity possible origin up uptick at shortest wavelengths (i.e., artifact)





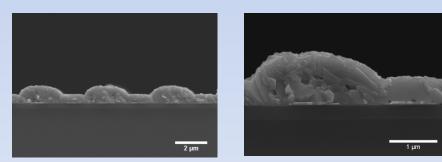
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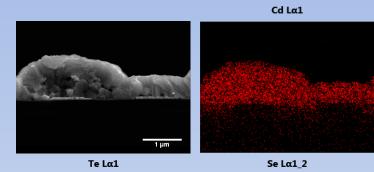
Back contact geometry gives flexibility

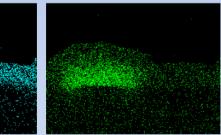
N-type material substitution without risk of blocking incoming light Might improve contact, junction, overall performance

Replace CdS with CdSe

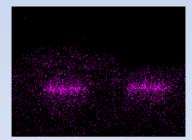
Lower bandgap ~1.7 eV is unacceptable for CdTe absorber with front contact/window layer Very thin (50 nm) iridium contacts - nonreactive







Ir Mα1



NIST

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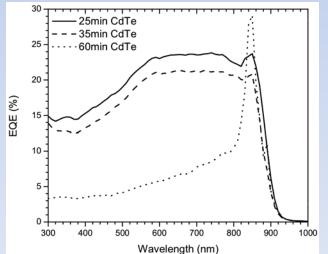
Improved EQE for ~0.6 and ~0.9 µm thick CdTe Decrease at shorter wavelengths not due to

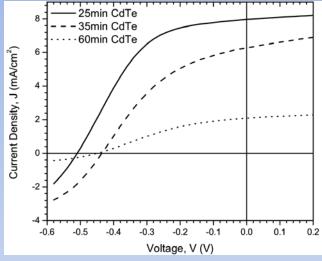
absorption in (nonexistent) window layer

Improved AM1.5 short circuit current and fill factor

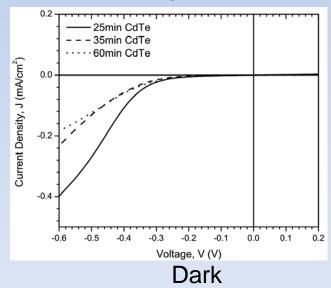
No voiding at the semiconductor/iridium electrode interfaces

Large work function iridium not ideal for n-type CdSe contact...





Light



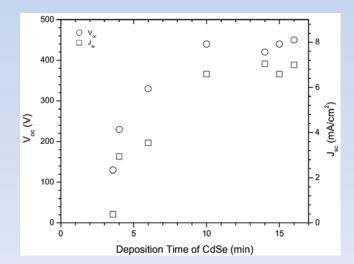
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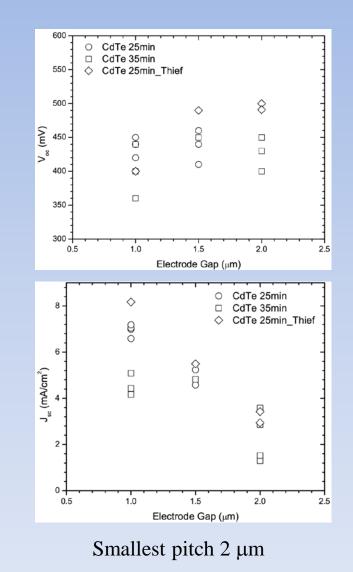
Performance depends on thickness of CdSe Too thin – pinholes lead to shunting, reducing V_{oc} and J_{sc}

Performance depends on electrode gap

Too wide, recombination occurs before charges can be collected, reducing ${\rm J}_{\rm sc}$

AM1.5 : Eff. 2.0%; V_{oc} 510 mV; J_{sc} 8 mA/cm²; fill factor 48% EQE: maximum 29%





CdSe/CdTe (PLD) Devices

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Higher quality CdTe – pulsed laser deposited (M. Sahiner, Seton Hall Univ.)

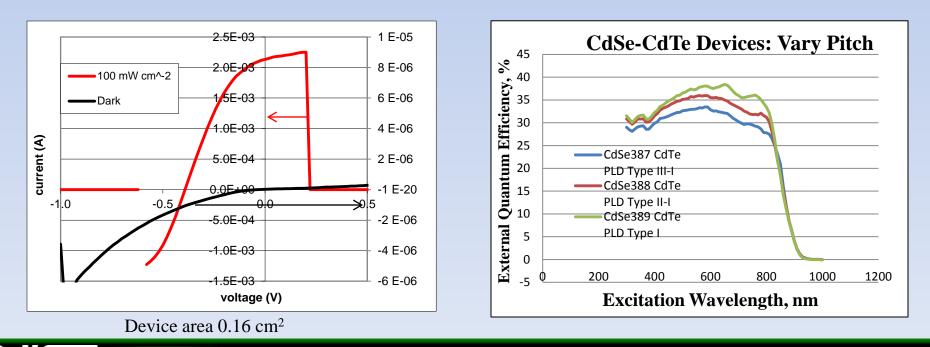
Short circuit current 60% higher at 13.5 mA/cm² and EQE exceeding 41%

 $V_{\rm oc}$ needs to be improved

Resistivity is less of an issue with higher quality CdTe – reduced dependence on pitch

The CdSe does not prevent incoming light from reaching the CdTe absorber

CdSe in front of the CdTe would absorb at ~730 nm; but it is behind.



Summary:

- Back contact geometry solar cells eliminating layers that block light and add to processing complexity
- CdS/CdTe devices traditional materials in back contact geometry
 - AM1.5: $J_{sc} = 4 \text{ mA/cm}^2$, $V_{oc} = 520 \text{ mV}$, ff = 39 % , Eff. = 0.9 %; Max EQE = 21%
- CdSe/CdTe devices taking advantage of the geometry to substitute materials
 - AM1.5: $J_{sc} = 8 \text{ mA/cm}^2$, $V_{oc} = 510 \text{ mV}$, ff = 48 % , Eff. = 2.0 %; Max EQE = 30%
- CdSe/CdTe (PLD) devices the role of material quality in device performance
 - AM1.5: $J_{sc} = 13 \text{ mA/gm}^2$, $V_{oc} = 400 \text{ mV}$, ff = 42 % , Eff. = 2.2 % Max EQE = 41%
 - These are early devices
- Back contact devices based on other materials and processes by other researchers

Ongoing Efforts

- Smaller dimensions
- Differentiated electrodes
- Surface passivation
- Other materials



Our Publications

D.U. Kim, C.M. Hangarter, R. Debnath, J.Y. Ha, C. R. Beauchamp, M.D. Widstrom, J.E. Guyer, N. Nguyen, B.Y. Yoo, and D. Josell, *Backcontact CdSe/CdTe Windowless Solar Cells*, Solar Energy Materials and Solar Cells, **In Press.**

C.M. Hangarter, B.H. Hamadani, J.E. Guyer, H. Xu, R. Need, and D. Josell, *Three Dimensionally Structured Interdigitated Back Contact Thin Film Heterojunction Solar Cells*, Journal of Applied Physics **109**, 073514 (2011).

D. Josell, C. R. Beauchamp, S. Jung, B.H. Hamadani, A. Motayed, L.J. Richter, M. Williams, J.E. Bonevich, A. Shapiro, N. Zhitenev, T.P. Moffat, *Three-Dimensionally Structured CdTe Thin Film Photovoltaic Devices with Self-Aligned Back-Contacts: Electrodeposition on Interdigitated Electrodes*, Journal of the Electrochemical Society **156**(8), H654-H660 (2009).



My Solar System

42 panels with 17.1% panel (19.3 % wafer) conversion efficiency and microinverters



NIST

Performance

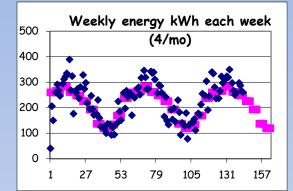
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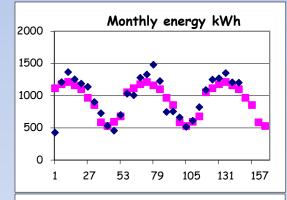
"Nameplate capacity" 9.02 kW DC Peak capacity ~ 8 kW AC Nominal Generation ~ 11 MWh/yr

Panels were highest available efficiency when installed Hip-roof : East/West panels are nonideal, mainly in winter as solar path sinks toward south

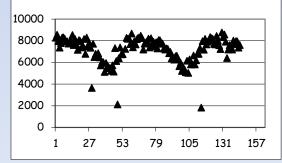
Tree coverage on west face













Impact on Electric Bill

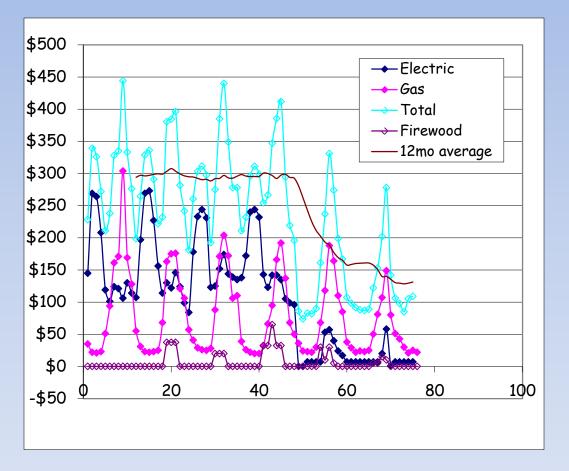
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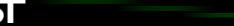
Our electric bill is:

\$7 /mo (fee) for two-thirds of the year

This reflects net metering carryover

Substantially reduced in winter months.





System Payback

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Amortization of total install cost

Payback:

2010:

30% Federal income tax credit

~\$7k MD grant

2012:

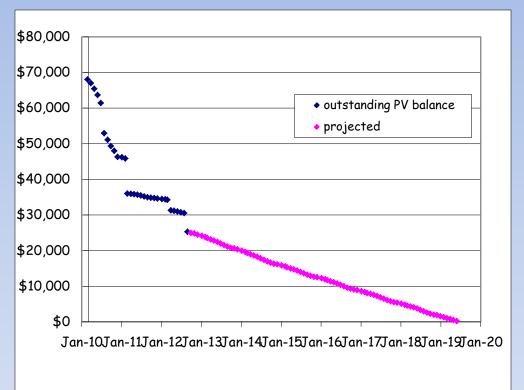
Mo.Co. \$5k property tax credit

Each Year:

Eleven Solar Renewable Energy Credits (SRECs)

Electric bill energy savings

Five years of ~\$100 state income tax credit



Premium panels added > \$1/watt – but high watt system lowered roof costs by \$1/watt



Pros:

Energy savings are always there but their value depends on the nature of your heating/cooling , utilization, etc.

Panels are much cheaper than when I installed my system

They are guaranteed to provide 80 % of nameplate value for 25 years (!)

Cons:

Does not address balance of system costs

County and state programs are no longer available

Future of federal credit is uncertain

SREC value has always been an unknown – recent state legislation aimed at stabilizing/raising it for a few years

I am as happy to discuss PV installation and installers as I am to discuss my research.



Thank you for your attention!

